# H&M400

## KÖNIG <sup>康尼格</sup>

## Single Station Low Pressure Molding Machine

低压注塑设备 (单枪)

适用于低压注塑热熔胶材料对电子元器件注塑封装保护,为敏感电子元器件,如: PCB/FPC, 传感器, 连接器, 线束, 电池等, 提供更优的封装保护。

The machines are engineered for Low Pressure Injection Molding applications. Using hot-melt adhesive material to protect delicate electronic components, such as PCB/FPC, sensors, connectors, wiring harness, batteries, etc.



#### 特点

- ·注胶系统采用高可靠性的齿轮泵和注胶枪,结构紧凑注 胶精准稳定。
- ·设备分段控温,胶缸、胶管和胶枪均可独立控制,温度 控制精准。
- •注胶压力通过面板压力阀进行调节,操作简便。
- ・操作台和熔胶系统采用分体布局,使用灵活。
- •操作台设有产品顶出装置,方便取出产品。
- •工作保护采用双手同时启动按钮,同时配备安全光栅。
- •采用标准模架设计,实现快速换模。
- •设备采用模块化设计,便于维护和保养,使用寿命长。

## FEATURES

- ·Injection system using high reliability gear pump and glue gun, to realize precise and stable injection with compact structure.
- •The cylinder, hose and gun can be controlled independently, and the temperature control is accurate.
- ·Injecting pressure is easy to adjust through the control panel.
- ·Work station and melt system adopts fission layout and uses flexible.
- •The operating table is equipped with an ejection device to facilitate the removal of products.
- $\cdot$  Working protection uses two-hands start button, also with infrared safety grating.
- •With standard mold design to realize rapid die change.
- •The equipment adopts modular design, which is easy to maintain

## 立式注胶 | 更大应用空间 | 单枪双枪可扩展适合复杂的多模穴和滑块机构的模具

Vertical injection nozzle, designed for large application space, single and double nozzle can be chose. Suitable for complex mold with multi cavities and slide mechanisms.



## 低压注塑工艺 Low Pressure Injection Molding











150~200℃ 极低的注塑温度 1.5~60bar 极低的注塑压力

成型速度快至1s

**IP67** 防水防尘

以上数据取决于具体产品,可能存在变化 Characters depend on project.

# H&M400



# Vertical injection Larger application space

立式注胶 | 更大应用空间

熔胶系统与数量 Melting Tank Model&Q'ty	KH05 (5 Liter)×1PC	
注胶枪型号与数量角度 Nozzle&Tip Angle	KG40×1PC(36°)	
注胶管型号与数量 Heated Hose Model&Q'ty	KJ16×1PC	
输入电压 Electricity	220VAC/1Phase/50 or 60Hz	
用气量 Air Consumption	0.1 m³/min	
温控分区 Temperature Control Zones	3	
最高设定温度 Max. Setting Temperature	up to 250°C	
最大功率 Max. Power	4.5Kw	
最低工作气压 Min. Air Pressure	0.5Mpa	
合模方式 Clamping Device	气缸(Cylinder)	
合模压力 Clamping Force	Max.1.2Ton	
合模行程 Clamping Stroke (mm)	150mm	
标准模具尺寸 Standard Mold Size(mm)	200×150×150	
最大模具尺寸 Max. Mold Size(mm)	300×200×150	
控制系统 Control System	PLC+7"HMI	
工作台高度 Work Station Height(mm)	940	
机台尺寸重量 Machine Size(mm)	830×800×1840 (373Kgs)	
包装尺寸重量 Packing Size(mm)	1030×1120×2040 (423Kgs)	

## 高生产效率 High Efficiency



## 高产品良率 High Yield



### 低温低压, 成型快速, 无损敏感 电子元器件

Perfect protect sensitive electronic components with low temperature & low pressure

No need plastic shell, no need

### 模具成型, 高一致性, 培训简单 操作便捷

High consistency with mold forming, easy to operate

## 节约材料

Save Material

一次快速成型



无需灌封外壳, 无需多次操作,

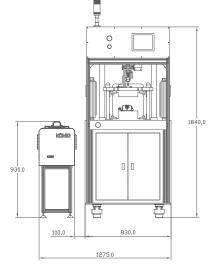
化学反应

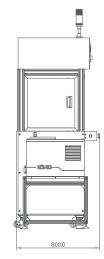
生产过程中无有毒烟气产生,无

No toxic smoke during production process

和谐生产环境

ECO Friendly





可选注胶平台	□ 立式注胶	□ 侧式注胶	☑ 单枪注胶	□ 双枪注胶
Injection Platform	Vertical type	Horizontal type	Left-right transfer mode	Single injection nozzle
可选配设备	□材料干燥机	□冷水机	口上下料机械手	□自动加料系统
Optional Equipment	Material dryer	Water chillers	Loading manipulators	Automatic feeding system

## 苏州康尼格电子科技股份有限公司 Suzhou KONIG Electronic Technology Co., Ltd

江苏省·苏州市·常熟辛庄镇长盛路33号 No.33 Changsheng Road, Xinzhuang, Changshu, Suzhou T+86-512-5247 9018 | F+86-512-5247 9098 | E info@konig.hk

